Power Transistors

PNP Silicon DPAK For Surface Mount Applications

Designed for high-gain audio amplifier and power switching applications.

Features

- Low Collector–Emitter Saturation Voltage $V_{CE(sat)} = 0.5 \text{ Vdc} (Max) @ I_C = -1 \text{ A}$
- High Switching Speed: $t_{STG} = 320$ ns (typ)
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V Machine Model, C > 400 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Base Voltage	V _{CB}	-50	Vdc
Collector-Emitter Voltage	V _{CEO}	-50	Vdc
Emitter-Base Voltage	V _{EB}	-5	Vdc
Collector Current Continuous Peak	Ι _C	-2 -3	Adc
Base Current	Ι _Β	-0.4	Adc
Total Device Dissipation @ T _C = 25°C Derate above 25°C	PD	15 0.1	W W/°C
Total Device Dissipation @ T _A = 25°C* Derate above 25°C	P _D	1.68 0.011	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction-to-Case Junction-to-Ambient*	$R_{ heta JC} \ R_{ heta JA}$	10 89.3	°C/W

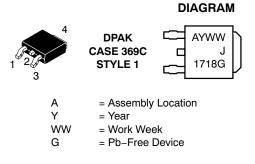
*These ratings are applicable when surface mounted on the minimum pad sizes recommended.



ON Semiconductor®

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SILICON POWER TRANSISTORS 2 AMPERES 50 VOLTS 15 WATTS



MARKING

ORDERING INFORMATION

Device	Package	Shipping [†]
NJD1718T4G	DPAK (Pb-Free)	2500 / Tape & Reel

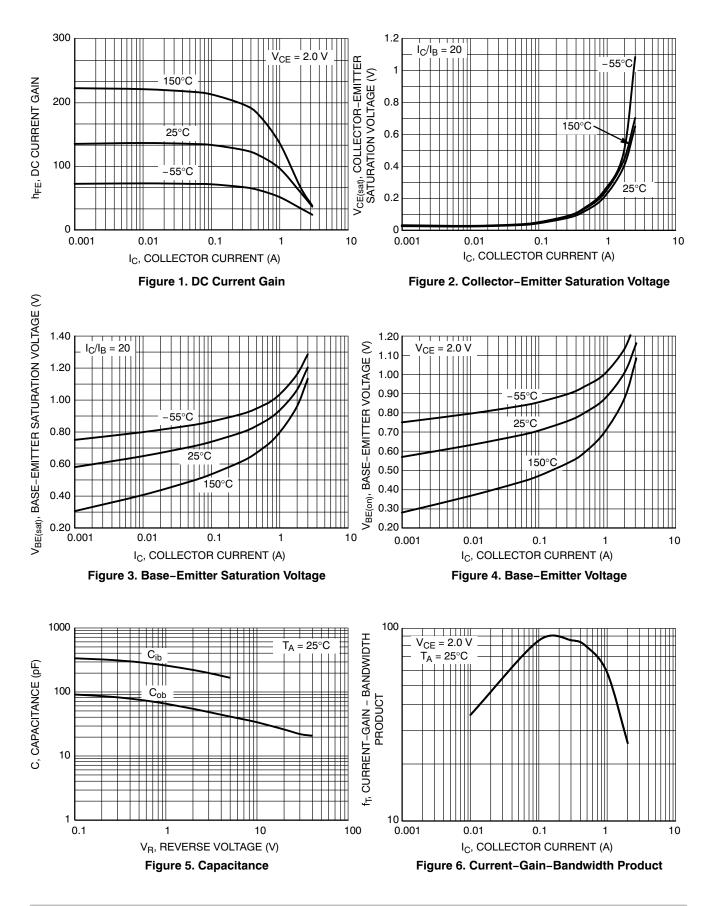
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_C = 25° C unless otherwise noted)

		1	r		
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	-				
Collector-Emitter Breakdown Voltage (Note 1) $(I_{C} = -10 \text{ mAdc}, I_{B} = 0)$	BV _{CEO}	-50		-	Vdc
Collector Cutoff Current (V _{CB} = -50 Vdc, I _E = 0)	I _{CBO}	_		-100	nAdc
Emitter Cutoff Current ($V_{BE} = -5 \text{ Vdc}, I_C = 0$)	I _{EBO}	-		-100	nAdc
ON CHARACTERISTICS					
DC Current Gain (Note 1) $(I_C = -0.5 \text{ A}, V_{CE} = 2 \text{ V})$ $(I_C = -1.5 \text{ Adc}, V_{CE} = 2 \text{ Vdc})$	h _{FE}	70 40		240 -	-
Collector–Emitter Saturation Voltage (Note 1) ($I_c = -1 A$, $I_B = -0.05 A$)	V _{CE(sat)}	_	-0.2	-0.5	Vdc
Base-Emitter Saturation Voltage (Note 1) ($I_c = -1 A$, $I_B = -0.05 Adc$)	V _{BE(sat)}	_	-	-1.2	Vdc
Base-Emitter On Voltage (Note 1) (I _C = -1 Adc, V _{CE} = -2 Vdc)	V _{BE(on)}	_	_	-1.2	Vdc
DYNAMIC CHARACTERISTICS					
Current–Gain – Bandwidth Product (Note 2) (I _C = –500 mAdc, V _{CE} = –2 Vdc, f _{test} = 10 MHz)	fT	-	80	-	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 0.1 MHz)	C _{ob}	-	33	-	pF
Switching Timers $V_{CC} = -30 \text{ V}, \text{ I}_{C} = -1 \text{ A}$	t _{ON}	-	55	-	ns
$I_{\rm B} = -50$ mA, $R_{\rm B} = 200 \ \Omega$	tsтg	-	320	-	
	t _f	-	40	-	

1. Pulse Test: Pulse Width = 300 $\mu s,$ Duty Cycle \approx 2%. 2. f_T = $\left|h_{fe}\right| \bullet f_{test}.$

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

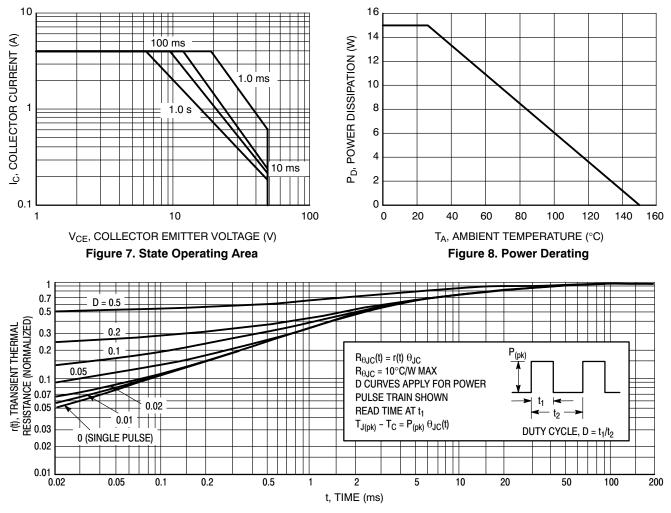
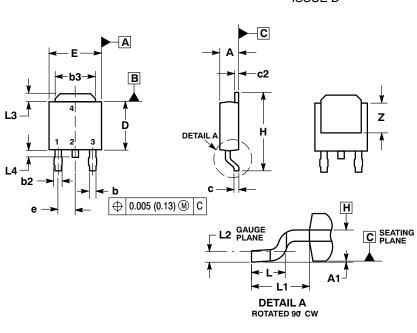


Figure 9. Thermal Response

PACKAGE DIMENSIONS



DPAK CASE 369C-01 ISSUE D

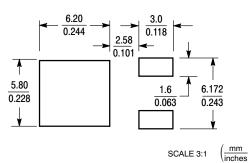
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

- Y14.5M, 1994.
 CONTROLLING DIMENSION: INCHES.
 THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 DIMENSIONS D AND E ABE DETERMINED AT THE
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H.

	INCHES		MILLIMETER		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
с	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
e	0.090 BSC		2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108 REF		2.74 REF		
L2	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

SOLDERING FOOTPRINT*



STYLE 1: PIN 1. BASE 2. COLLECTOR

3. EMITTER

4 COLLECTOR

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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